RICOH

100 mA Ultra-low Supply Current (0.3 µA) LDO Regulator with Battery Monitor

No. EA-503-191025

OVERVIEW

The RP124x is an LDO regulator with a battery monitor (BM) featuring ultra-low supply current. The battery monitor has a function which divides the input voltage (V_{IN}) into 1/3 or 1/4. The battery charge remaining can be monitored by MCU. The buffering output enables directly inputting a signal into the low voltage A/D converter (ADC) with built-in MCU.

KEY BENEFITS

- Achieving Low Supply Current of 0.3 μA, Longer Battery Life and Downsizing
- Requiring Only Three External Capacitors and Suitable for Space-saving Mounting for the Smaller Packages

KEY SPECIFICATIONS

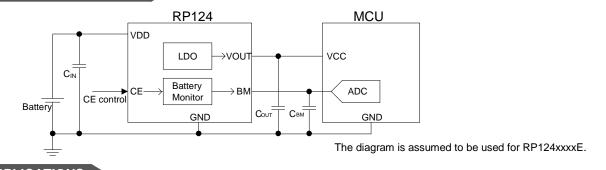
LDO Section

- Input Voltage Range: 1.7 V to 5.5 V
- Supply Current: Typ. 0.2 µA
- Output Voltage Accuracy: ±0.8%
- Output Current: 100 mA
- Ceramic Capacitor Compatible: 1.0 µF or more

BM Section

- Output Voltage: V_{IN}/3 (RP124xxx3x) V_{IN}/4 (RP124xxx4x)
- Supply Current: Typ. 0.1 µA
- Ceramic Capacitor Compatible: 0.1 µF to 0.22 µF

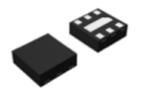




APPLICATIONS

- Battery powered IoT devices
- Energy harvesting devices
- Low power wireless communication modules including: Bluetooth® LE, Zigbee, and LPWA
- Low power consumption CPUs, memories, and sensors

PACKAGES





DFN1212-6 1.2 mm x 1.2 mm x 0.4 mm

SOT-23-5 2.9 mm x 2.8 mm x 1.1 mm

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SELECTION GUIDE

The LDO set output voltage, the divided ratio of BM output voltage, the CE pin function and the auto-discharge function are user-selectable options.

Selection Guide

Product Name	Package	Quantity per Reel	Pb Free	Halogen Free	
RP124Lxx#*-TR	DFN1212-6	5,000 pcs	Yes	Yes	
RP124Nxx#*-TR-FE	SOT-23-5	3,000 pcs	Yes	Yes	

xx: Specify the LDO set output voltage (V_{SET}).

1.2 V (12) / 1.5 V (15) / 1.8 V (18) / 2.1 V (21) / 2.2 V (22) / 2.3 V (23) / 2.4 V (24) / 2.5 V (25) / 2.7 V (27) / 2.8 V (28) / 3.0 V (30) / 3.1 V (31) / 3.3 V (33) / 3.6 V (36) Contact Ricoh sales representatives for other voltages.

#: Specify the divided ratio of BM output voltage.

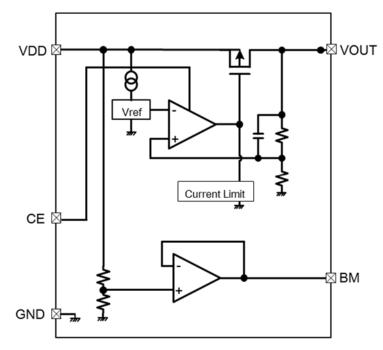
- 3: VIN/3
- 4: V_{IN}/4

*: Specify the CE pin and the auto-discharge option.

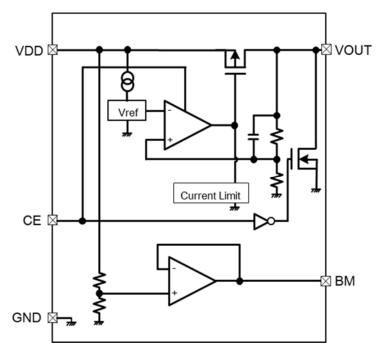
*	CE pin	Auto-dis	charge
Б	Controlling I DO with the CE pin (Active high)	LDO	No
В	Controlling LDO with the CE pin (Active-high)	BM	No
	Controlling I DO with the CE pin (Active high)	LDO	Yes
D	Controlling LDO with the CE pin (Active-high)	BM	No
		LDO	No
E	Controlling BM with the CE pin (Active-high)	BM	Yes

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BLOCK DIAGRAMS

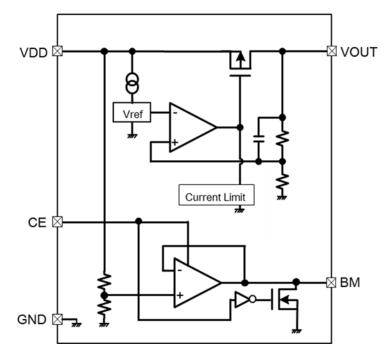


RP124xxxxB Block Diagram



RP124xxxxD Block Diagram

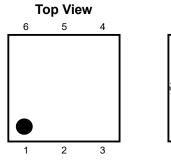
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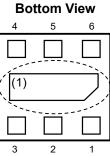


RP124xxxxE Block Diagram

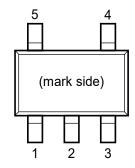
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PIN DESCRIPTIONS





RP124L (DFN1212-6) Pin Configuration



RP124N (SOT-23-5) Pin Configuration

RP124L (DFN1212-6) Pin Description

Pin No.	Symbol	Description	
1	VOUT	Output Pin	
2	GND	Ground Pin	
3	BM	Battery Monitoring Output Pin	
4	CE	Chip Enable Pin, Active-high	
5	NC	No Connection	
6	VDD	Input Pin	

RP124N (SOT-23-5) Pin Description

Pin No.	Symbol	Description
1	VDD	Input Pin
2	GND	Ground Pin
3	CE	Chip Enable Pin, Active-high
4	BM	Battery Monitoring Output Pin
5	VOUT	Output Pin

⁽¹⁾ The tab on the bottom of the package enhances thermal performance and is electrically connected to GND (substrate level). It is recommended that the tab be connected to the ground plane on the board, or otherwise be left floating.



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ABSOLUTE MAXIMUM RATINGS

Absolute Maximum Ratings

Symbol		Item	Rating	Unit
VIN	Input Voltage		-0.3 to 6.5	V
V _{CE}	CE Pin Voltage	9	-0.3 to 6.5	V
Vout	VOUT Pin Volt	-0.3 to V _{IN} + 0.3	V	
VBM	BM Pin Voltage	-0.3 to V _{IN} + 0.3	V	
IOUT	Output Current		130	mA
D-	Power	DFN1212-6 (JEDEC STD. 51-7 Test Land Pattern)	850	mW
PD	Dissipation ⁽¹⁾ SOT-23-5 (JEDEC STD. 51-7 Test Land Pattern)		660	mW
Tj	Junction Temp	-40 to 125	°C	
Tstg	Storage Temp	erature Range	-55 to 125	°C

ABSOLUTE MAXIMUM RATINGS

Electronic and mechanical stress momentarily exceeded absolute maximum ratings may cause permanent damage and may degrade the life time and safety for both device and system using the device in the field. The functional operation at or over these absolute maximum ratings is not assured.

RECOMMENDED OPERATING CONDITIONS

Recommended Operating Conditions

Symbol	Item	Rating	Unit	
Max		RP124xxx3x	1.7 to 5.5	V
V _{IN} Input Vol	Input Voltage	RP124xxx4x	2.4 to 5.5	v
Та	Ta Operating Temperature		-40 to 85	°C

RECOMMENDED OPERATING CONDITIONS

All of electronic equipment should be designed that the mounted semiconductor devices operate within the recommended operating conditions. The semiconductor devices cannot operate normally over the recommended operating conditions, even if they are used over such conditions by momentary electronic noise or surge. And the semiconductor devices may receive serious damage when they continue to operate over the recommended operating conditions.

⁽¹⁾ Refer to POWEWR DISSIPATION for detailed information.

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ELECTRICAL CHARACTERISTICS

 $V_{IN} = V_{SET} + 1.0 \text{ V}, I_{OUT} = 1.5 \text{ mA}, C_{IN} = C_{OUT} = 1.0 \mu\text{F}$, unless otherwise noted. The specifications surrounded by ______ are guaranteed by design engineering at -40°C ≤ Ta ≤ 85°C.

RP124x B	RP124x Electrical Characteristics: LDO Section(Ta = 25°C)						
Symbol	Parameters	Test Cond	ditions	Min.	Тур.	Max.	Unit
		V _{SET} > 2.0 V		x0.992 x0.987		x1.008 x1.013	V
Vout	Output Voltage	$V_{\text{SET}} \leq 2.0 \text{ V}$		-16 -26		16 26	mV
Іоит	Output Current			100			mA
	Output Voltage		V _{SET} > 2.0 V	-1		1	%
ΔV out	Deviation When Switching Mode	1 µA ≤ louт ≤ louтн	$V_{\text{SET}} \leq 2.0 \ \text{V}$	-20		20	mV
ΔVουτ /ΔΙουτ	Load Regulation	$1.5 \text{ mA} \le I_{OUT} \le 100 \text{ mA}$		-40	2	40	mV
V _{DIF}	Dropout Voltage	I _{OUT} = 100 mA				duct-spe haracteri	
lss	Supply Current	Vce = Vin, Iout = 0 mA			0.2	0.42	μΑ
			Υ.			0.5	μA
Іоитн	Fast Mode Switching Current	$I_{OUT} =$ From Light Loa $V_{IN} = 5.0 V$	I_{OUT} = From Light Load to Heavy Load, V_{IN} = 5.0 V		0.5		mA
IOUTL	Low Power Mode Switching Current	Iout = From Heavy Lo V _{IN} = 5.0 V	oad to Light Load,	0.08			mA
ΔV_{OUT}	Line Regulation	$V_{SET} + 0.5 \text{ V} \leq V_{IN} \leq 5.5 \text{ V}$			0.02	0.2	%/V
lsc	Short Current Limit	V _{OUT} = 0 V			65		mA
Vсен	CE Pin Input Voltage, high	RP124xxxxB/D		1.0			V
V _{CEL}	CE Pin Input Voltage, low	RP124xxxxB/D				0.4	V
R _{DISN}	Auto-discharge NMOS On-resistance	$V_{IN} = 4.0 \text{ V}, \text{ V}_{CE} = 0 \text{ V}$	/, RP124xxxxD		50		Ω

All test items listed under Electrical Characteristics are done under the pulse load condition Tj \approx Ta = 25°C.

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ELECTRICAL CHARACTERISTICS (continued)

The specifications surrounded by \square are guaranteed by design engineering at $-40^{\circ}C \le Ta \le 85^{\circ}C$.

.			Vou	т [V]			v	r\/1	
Product Name	Ta = 25°C			-40	-40°C ≤ Ta ≤ 85°C			V _{DIF} [V]	
Name	Min.	Тур.	Max.	Min.	Тур.	Max.	Тур.	Max.	
RP124x12xx	1.184	1.200	1.216	1.174	1.200	1.226	0.640	0.975	
RP124x15xx	1.484	1.500	1.516	1.474	1.500	1.526	0.410	0.660	
RP124x18xx	1.784	1.800	1.816	1.774	1.800	1.826	0.230	0.380	
RP124x21xx	2.084	2.100	2.116	2.073	2.100	2.127	0.150	0.285	
RP124x22xx	2.183	2.200	2.217	2.172	2.200	2.228			
RP124x23xx	2.282	2.300	2.318	2.271	2.300	2.329	0.130	0.230	
RP124x24xx	2.381	2.400	2.419	2.369	2.400	2.431			
RP124x25xx	2.480	2.500	2.520	2.468	2.500	2.532	0.110	0.190	
RP124x27xx	2.679	2.700	2.721	2.665	2.700	2.735	0.110	0.180	
RP124x28xx	2.778	2.800	2.822	2.764	2.800	2.836			
RP124x30xx	2.976	3.000	3.024	2.961	3.000	3.039	0.100	0.160	
RP124x31xx	3.076	3.100	3.124	3.060	3.100	3.140			
RP124x33xx	3.274	3.300	3.326	3.258	3.300	3.342	0.000	0 1 4 5	
RP124x36xx	3.572	3.600	3.628	3.554	3.600	3.646	0.090	0.145	

RP124x Product-specific Electrical Characteristics: LDO Section

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ELECTRICAL CHARACTERISTICS (continued)

 C_{IN} = 1.0 $\mu F,\,C_{\text{BM}}$ = 0.22 $\mu F,$ unless otherwise noted.

The specifications surrounded by \square are guaranteed by design engineering at $-40^{\circ}C \le Ta \le 85^{\circ}C$.

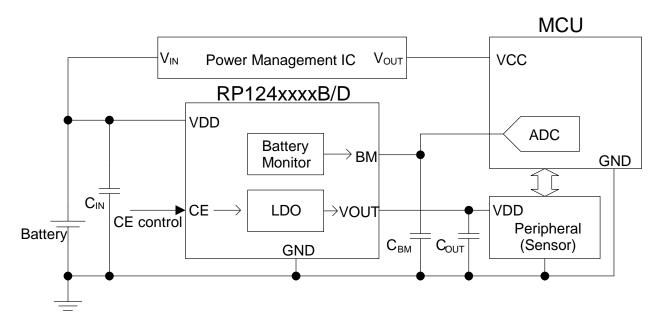
RP124x	RP124x Electrical Characteristics: Battery Monitor Section (Ta = 25°C)						
Symbol	Parameters	Test Con	ditions	Min.	Тур.	Max.	Unit
			1.7 V ≤ V _{IN} ≤ 5.5 V,	V _{IN} /3-20	V _{IN} /3	V _{IN} /3+20	
Maria		−10 μA ≤ I _{BM} ≤ 10 μA	RP124xxx3x	V _{IN} /3-25	V _{IN} /3	VIN/3+25	m\/
VBM	Output Voltage		$2.4 \text{ V} \le \text{V}_{\text{IN}} \le 5.5 \text{ V},$	V _{IN} /4-20	V _{IN} /4	V _{IN} /4+20	mV
				V _{IN} /4-25	V _{IN} /4	V _{IN} /4+25	
	Quitout Curroot	1.7 V ≤ V _{IN} ≤ 5.5 V, R	1.7 V ≤ V _{IN} ≤ 5.5 V, RP124xxx3x			10	
Івм	Output Current	2.4 V ≤ V _{IN} ≤ 5.5 V, RP124xxx4x		-10		10	μA
I _{SSBM}	Supply Current	$V_{\text{IN}} = V_{\text{CE}} = 3.6 \text{ V} \text{ , } I_{\text{BN}}$	1 = 0 μA		0.1	0.2	μA
Manual	CE Pin Input	1.7 V ≤ V _{IN} ≤ 5.5 V, R	P124xxx3E	4.0			V
Vсенвм	Voltage, high	$2.4 \text{ V} \le \text{V}_{\text{IN}} \le 5.5 \text{ V}, \text{ R}$	P124xxx4E	1.0			V
N/	CE Pin Input	1.7 V ≤ V _{IN} ≤ 5.5 V, R	P124xxx3E			6.4	V
VCELBM	Voltage, low	2.4 V ≤ V _{IN} ≤ 5.5 V, RP124xxx4E				0.4	V
Rdisnbm	Auto-discharge NMOS On- resistance	$V_{\text{IN}} = 4.0 \text{ V}, \text{ V}_{\text{CE}} = 0 \text{ V}$, RP124xxxxE		50		Ω

All test items listed under Electrical Characteristics are done under the pulse load condition Tj \approx Ta = 25°C.

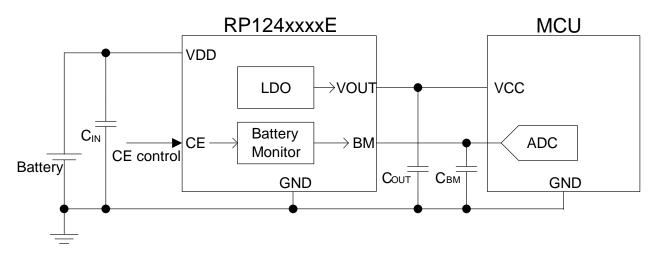
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APPLICATION INFORMATION

TYPICAL APPLICATION

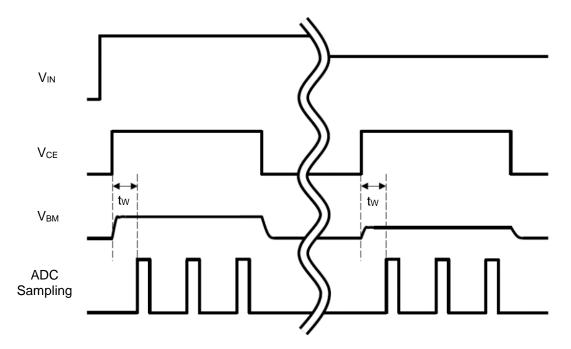


RP124xxxxB/D Typical Application Circuit



RP124xxxxE Typical Application Circuit

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Timing Chart Example of RP124xxxxE Circuit

The above diagram shows the example of using the RP124xxxxE typical application circuit and its timing chart. Connecting BM pin and ADC input pin of MCU enables monitoring the battery voltage. Controlling the start-up and stop of Battery Monitor with CE pin by the timing based on the ADC sampling reduces power consumption of the entire system. When monitoring the battery voltage, set the waiting time (tw) in order to stabilize waveform after the CE input voltage is set to "H". It is recommended to set tw \geq 10 ms for this product.

Notes on External Components

- Phase compensation is provided to secure stable operation even when the load current is varied. For this purpose, use a 1.0-µF or more output capacitor (C_{OUT}) between the VOUT and GND pins, and a 0.1-µF to 0.22-µF capacitor (C_{BM}) between the BM and GND pins with shortest-distance wiring. In case of using a tantalum type capacitor with a large ESR (Equivalent Series Resistance), the output might become unstable. Evaluate your circuit including consideration of frequency characteristics.
- Connect a 1.0-µF or more input capacitor (C_{IN}) between the VDD and GND pins with shortest-distance wiring.

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TECHNICAL NOTES

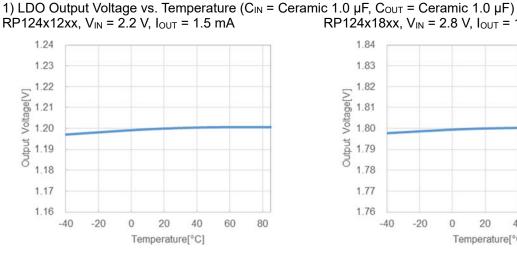
The performance of a power source circuit using this device is highly dependent on a peripheral circuit. A peripheral component or the device mounted on PCB should not exceed its rated voltage, rated current or rated power. When designing a peripheral circuit, please be fully aware of the following points.

- The high impedance of the wirings may result in noise pickup and unstable operation of the device. Reduce the impedance of the VDD and GND wirings.
- When an intermediate voltage other than V_{IN} or GND is input to the CE pin, a supply current may be increased with a through current of a logic circuit in the IC. The CE pin is neither pulled up nor pulled down, therefore an operation is not stable at open.

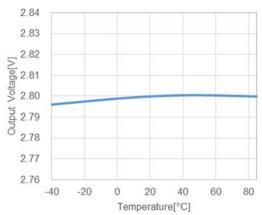
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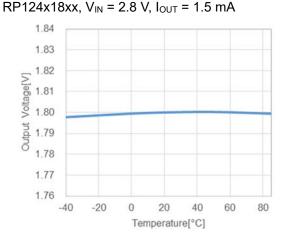
TYPICAL CHARACTERISTICS

Typical Characteristics are intended to be used as reference data; they are not guaranteed.

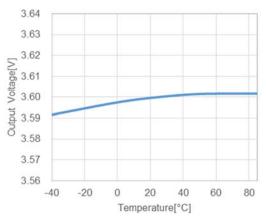


RP124x28xx, V_{IN} = 3.8 V, I_{OUT} = 1.5 mA

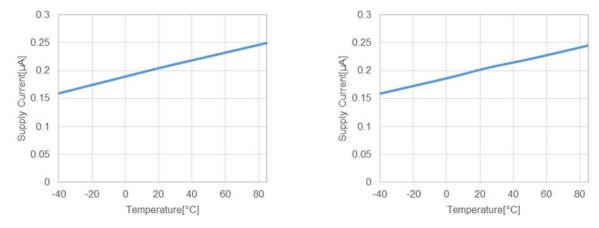




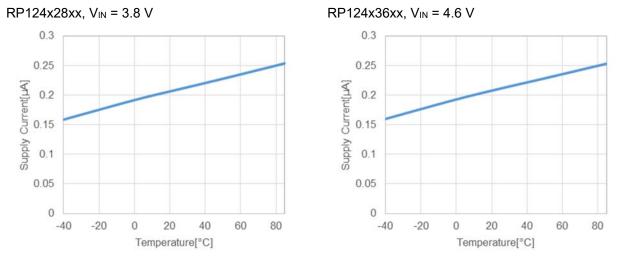
RP124x36xx, V_{IN} = 4.6 V, I_{OUT} = 1.5 mA



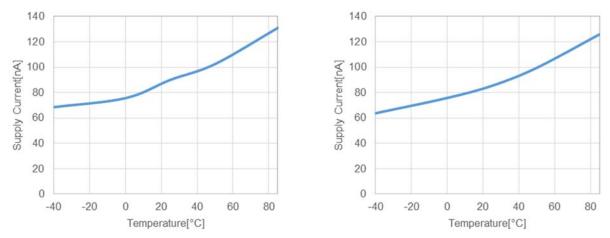
2) LDO Supply Current vs. Temperature (C_{IN} = Ceramic 1.0 µF, C_{OUT} = Ceramic 1.0 µF) RP124x12xx, V_{IN} = 2.2 V RP124x18xx, V_{IN} = 2.8 V



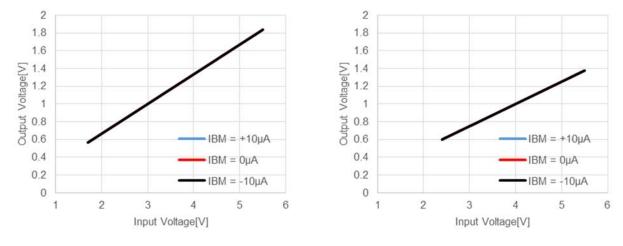
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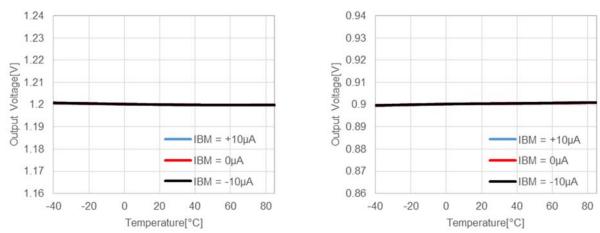
3) BM Supply Current vs. Temperature (C_{IN} = Ceramic 1.0 µF, C_{BM} = Ceramic 0.1 µF) RP124xxx3x, V_{IN} = 3.6 V RP124xxx4x, V_{IN} = 3.6 V



4) BM Output Voltage vs. Input Voltage (C_{IN} = Ceramic 1.0 μ F, C_{BM} = Ceramic 0.1 μ F, Ta = 25°C) RP124xxx3x RP124xxx4x

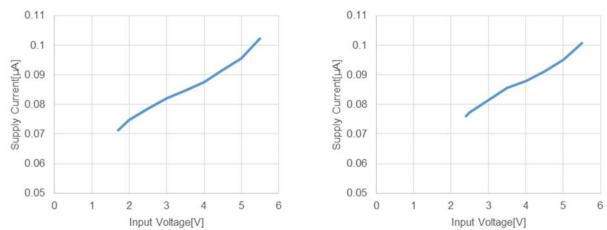


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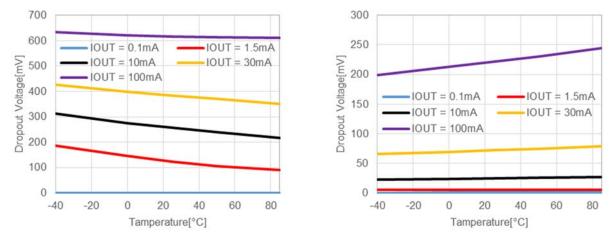


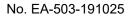
5) BM Output Voltage vs. Temperature (C_{IN} = Ceramic 1.0 μ F, C_{BM} = Ceramic 0.1 μ F) RP124xxx3x, V_{IN} = 3.6 V RP124xxx4x, V_{IN} = 3.6 V

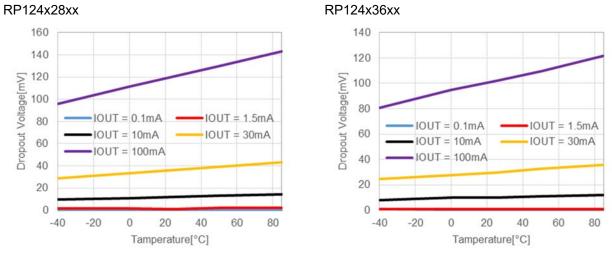
6) BM Supply Current vs. Input Voltage (C_{IN} = Ceramic 1.0 μ F, C_{BM} = Ceramic 0.1 μ F, Ta = 25°C) RP124xxx3x RP124xxx4x



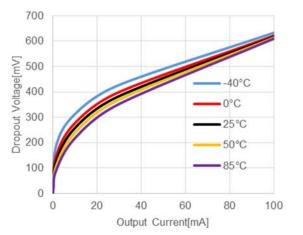
7) LDO Dropout Voltage vs. Temperature (C_{IN} = Ceramic 1.0 μ F, C_{OUT} = Ceramic 1.0 μ F) RP124x12xx RP124x18xx

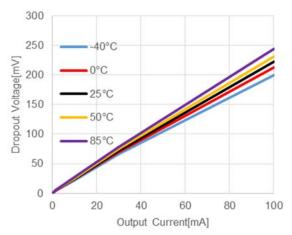




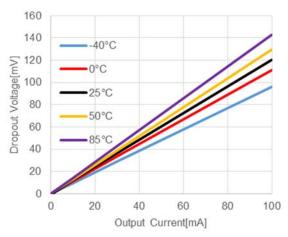


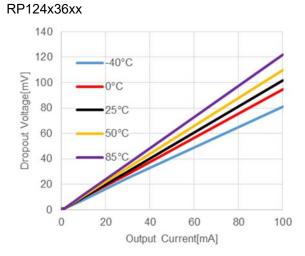
8) LDO Dropout Voltage vs. Output Current (C_{IN} = Ceramic 1.0 μF, C_{OUT} = Ceramic 1.0 μF) RP124x12xx RP124x18xx





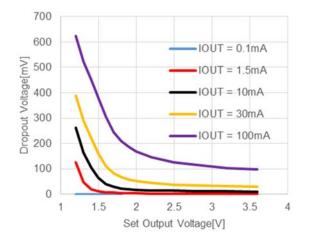






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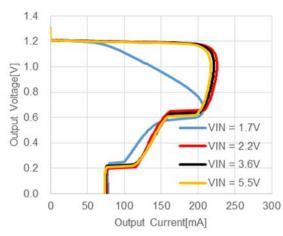
No. EA-503-191025

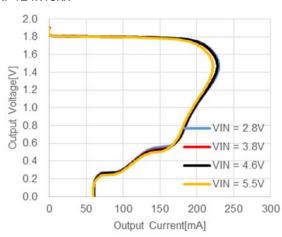


9) LDO Dropout Voltage vs. Set Output Voltage (C_{IN} = Ceramic 1.0 µF, C_{OUT} = Ceramic 1.0 µF, Ta = 25°C)

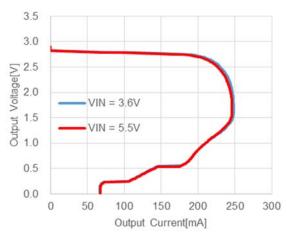
10) LDO Output Voltage vs. Output Current (C_{IN} = Ceramic 1.0 µF, C_{OUT} = Ceramic 1.0 µF, Ta = 25°C) RP124x12xx RP124x18xx

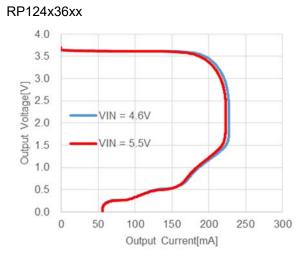
RICOH



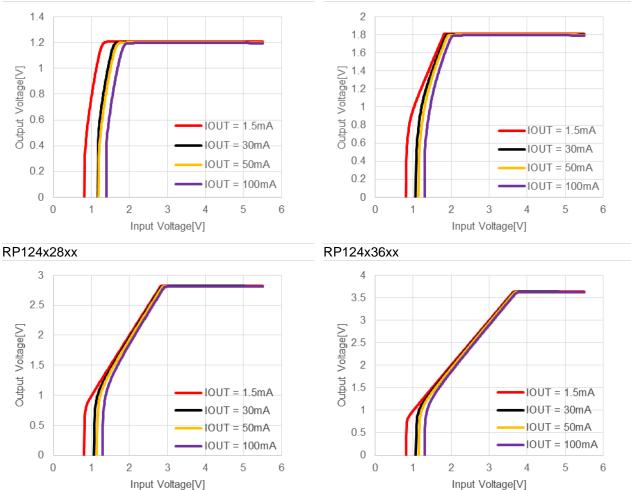


RP124x28xx



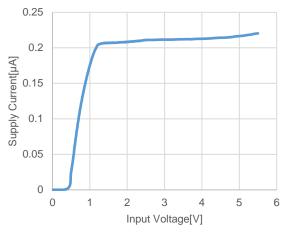


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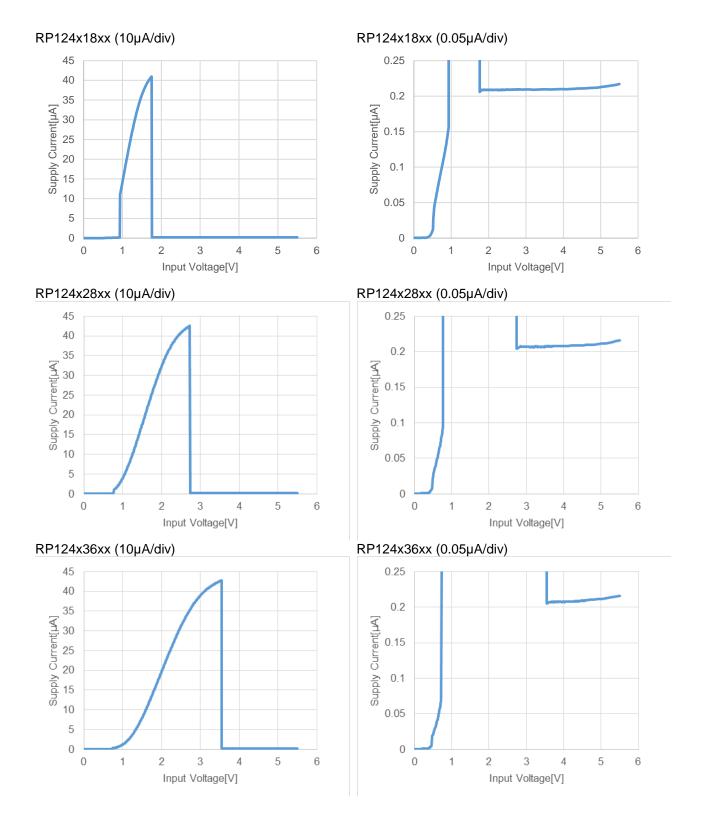


11) LDO Output Voltage vs. Input Voltage (C_{IN} = Ceramic 1.0 μ F, C_{OUT} = Ceramic 1.0 μ F, Ta = 25°C) RP124x12xx RP124x18xx

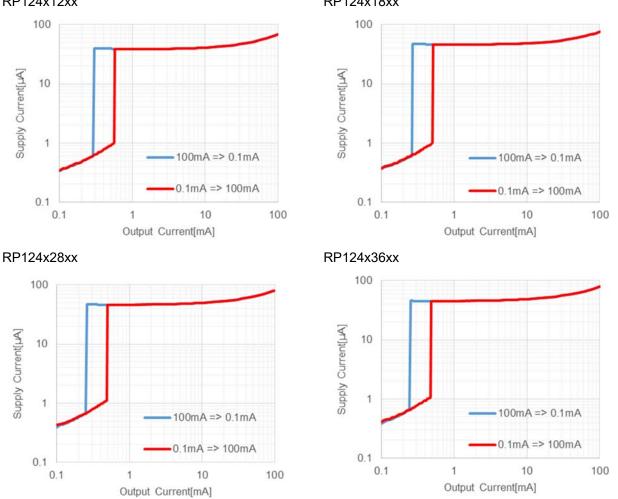
12) LDO Supply Current vs. Input Voltage (C_{IN} = Ceramic 1.0 μ F, C_{OUT} = Ceramic 1.0 μ F, Ta = 25°C) RP124x12xx



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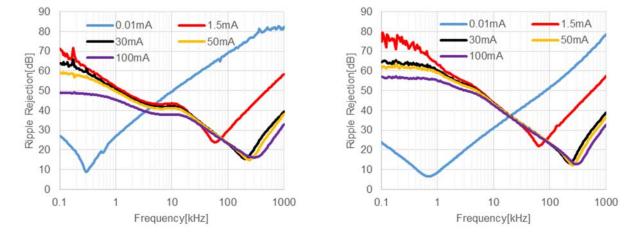


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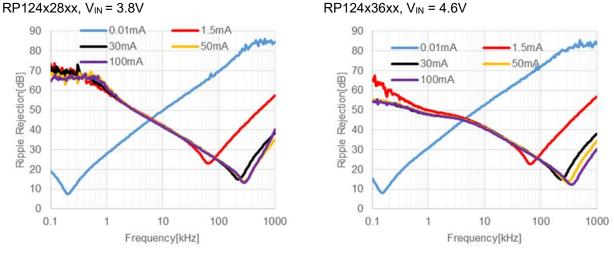
13) LDO Supply Current vs. Output Current (C_{IN} = Ceramic 1.0 μ F, C_{OUT} = Ceramic 1.0 μ F, Ta = 25°C) RP124x12xx RP124x18xx

14) Ripple Rejection vs. Frequency (C_{IN} = none, C_{OUT} = Ceramic 1.0 µF, Ta = 25°C) RP124x12xx, V_{IN} = 2.2 V RP124x18xx, V_{IN} = 2.8 V

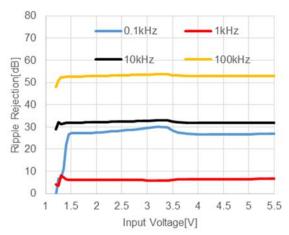


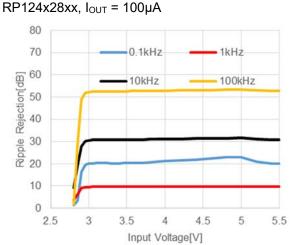
RICOH

No. EA-503-191025

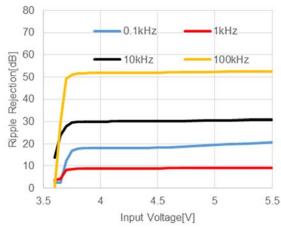


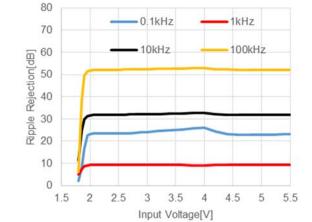
15) Ripple Rejection vs. Input Voltage (C_{IN} = none, C_{OUT} = Ceramic 1.0 µF, Ta = 25°C) RP124x12xx, Iout = 100 µA RP124x18xx, Iout = 100 µA

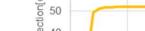




RP124x36xx, I_{OUT} = 100µA





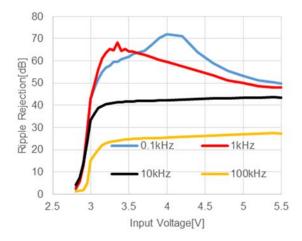


RICOH

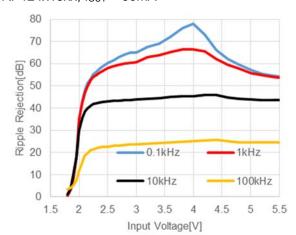
No. EA-503-191025



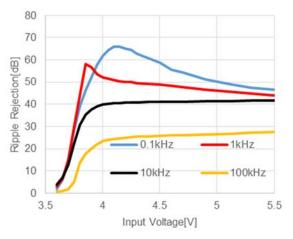
RP124x28xx, I_{OUT} = 30mA



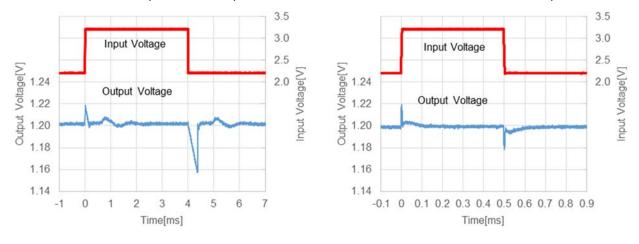
RP124x18xx, I_{OUT} = 30mA



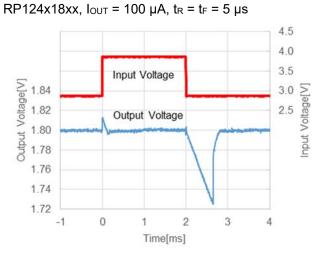


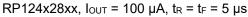


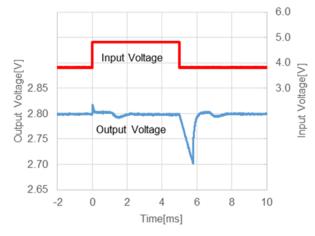
16) LDO Input Transient Response (C_{IN} = Ceramic 0.1 μ F, C_{OUT} = Ceramic 1.0 μ F, Ta = 25°C) RP124x12xx, I_{OUT} = 100 μ A, t_R = t_F = 5 μ s RP124x12xx, I_{OUT} = 30 mA, t_R = t_F = 5 μ s



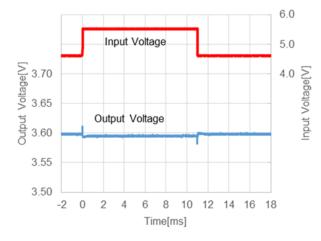
No. EA-503-191025

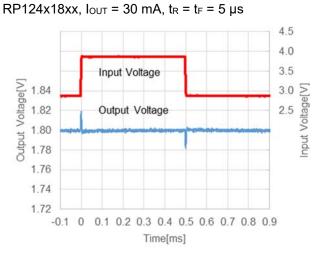




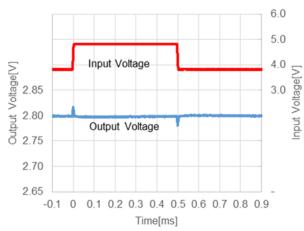


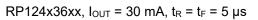


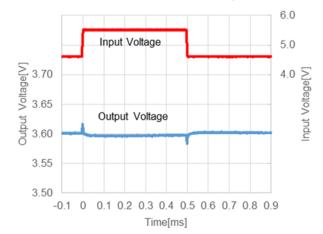




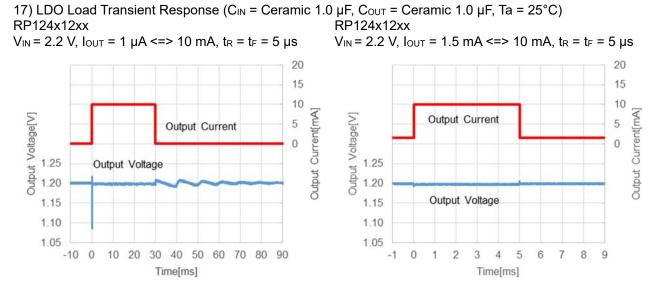
RP124x28xx, I_{OUT} = 30 mA, t_R = t_F = 5 µs



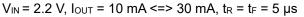


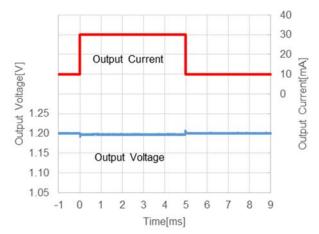


No. EA-503-191025

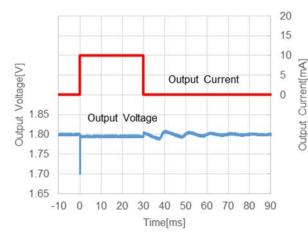


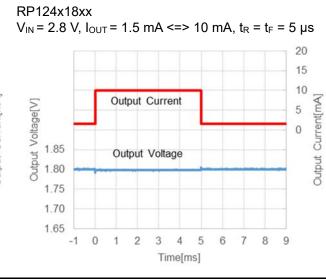
RP124x12xx





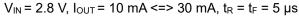
RP124x18xx V_{IN} = 2.8 V, I_{OUT} = 1 μ A <=> 10 mA, t_R = t_F = 5 μ s

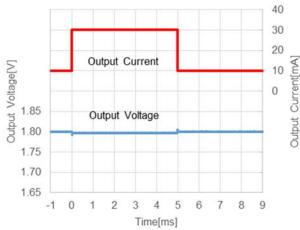




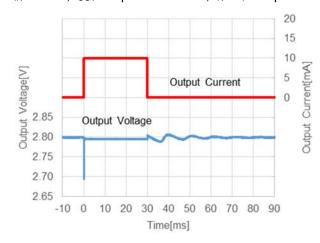
No. EA-503-191025

RP124x18xx

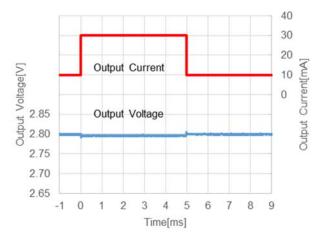




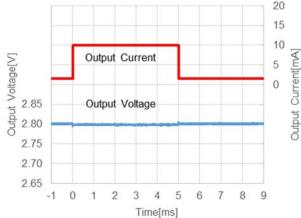
RP124x28xx V_{IN} = 3.8 V, I_{OUT} = 1 μ A <=> 10 mA, t_R = t_F = 5 μ s



RP124x28xx V_{IN} = 3.8 V, I_{OUT} = 10 mA <=> 30 mA, t_R = t_F = 5 µs

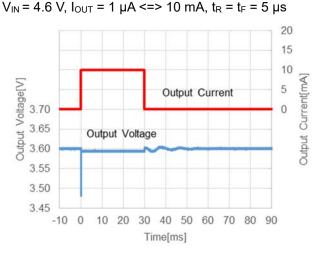


RP124x28xx V_{IN} = 3.8 V, I_{OUT} = 1.5 mA <=> 10 mA, t_R = t_F = 5 µs 20

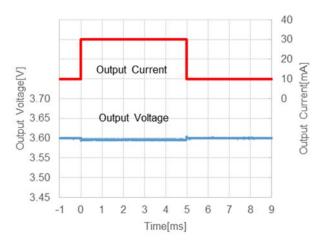


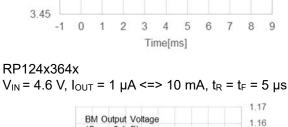
No. EA-503-191025

RP124x36xx



RP124x36xx $V_{IN} = 4.6 \text{ V}, I_{OUT} = 10 \text{ mA} <=> 30 \text{ mA}, t_R = t_F = 5 \text{ }\mu\text{s}$





 V_{IN} = 4.6 V, I_{OUT} = 1.5 mA <=> 10 mA, t_R = t_F = 5 µs

Output Current

Output Voltage

20 15

10

5

0

Output Current[mA]

RP124x36xx

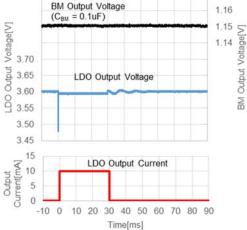
Output Voltage[V]

3.70 3.65

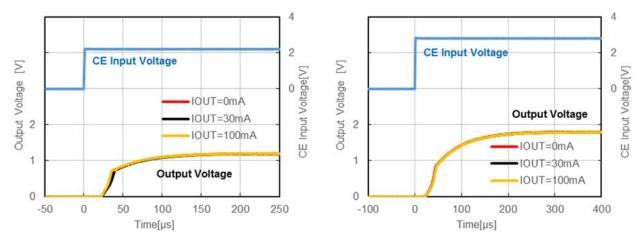
3.60

3.55

3.50



18) LDO Turning-on with CE Pin (C_{IN} = Ceramic 1.0 μ F, C_{OUT} = Ceramic 1.0 μ F, Ta = 25°C) RP124x12xD, V_{IN} = 2.2 V, V_{CE} = 0 V => 2.2 V RP124x18xD, V_{IN} = 2.8 V, V_{CE} = 0 V => 2.8 V



RICOH

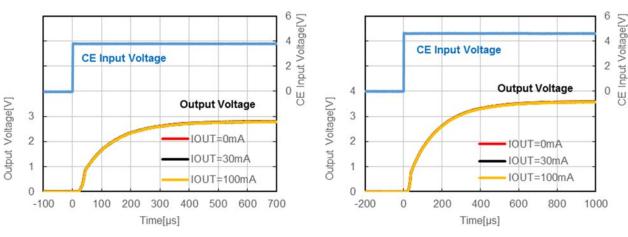
4

2

CE Input Voltage[V]

0.6

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19) LDO Turning-off with CE Pin (C_{IN} = Ceramic 1.0 µF, C_{OUT} = Ceramic 1.0 µF, Ta = 25°C) RP124x12xD, V_{IN} = 2.2 V, V_{CE} = 2.2 V => 0 V RP124x18xD, V_{IN} = 2.8 V, V_{CE} = 2.8 V => 0 V

Σ

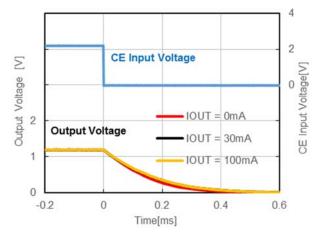
Output Voltage

2

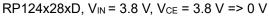
1

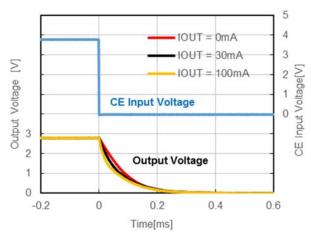
0

-0.2



RP124x28xD, V_{IN} = 3.8 V, V_{CE} = 0 V => 3.8 V





RP124x36xD, V_{IN} = 4.6 V, V_{CE} = 4.6 V => 0 V

CE Input Voltage

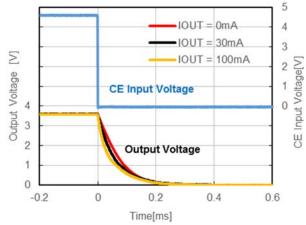
0.2

IOUT = 0mA

IOUT = 30mA

IOUT = 100mA

0.4



Time[ms]

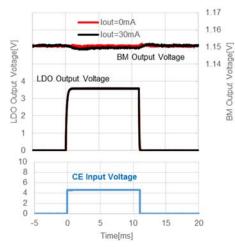
Output Voltage

0

RP124x36xD, V_{IN} = 4.6 V, V_{CE} = 0 V => 4.6 V

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RP124x364D, V_{IN} = 4.6 V, V_{CE} = 0 V <=> 4.6 V



20) BM Turning-on/off with CE Pin (C_{IN} = Ceramic 1.0 μ F, C_{BM} = Ceramic 0.1 μ F, 0.22 μ F, Ta = 25°C) RP124xxx3x, V_{IN} = 3.6 V, V_{CE} = 0 V <=> 3.6 V RP124xxx4x, V_{IN} = 3.6 V, V_{CE} = 0 V <=> 3.6 V

> Output Voltage[V] 1.5

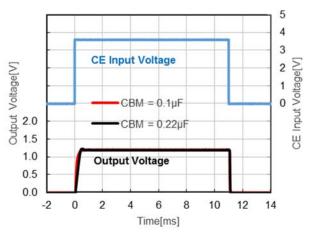
1.0

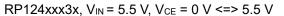
0.5

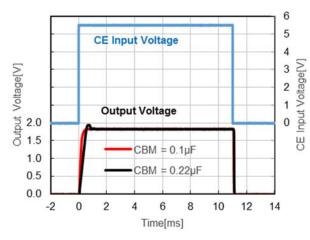
0.0

-2

0







RP124xxx4x, V_{IN} = 5.5 V, V_{CE} = 0 V <=> 5.5 V

2

Output Voltage

4

CE Input Voltage

 $CBM = 0.1 \mu F$

CBM = 0.22µF

6

Time[ms]

10

8

12

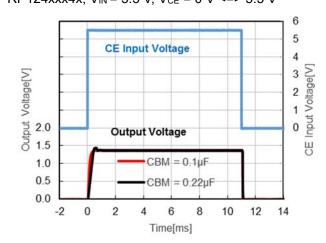
14

5

4

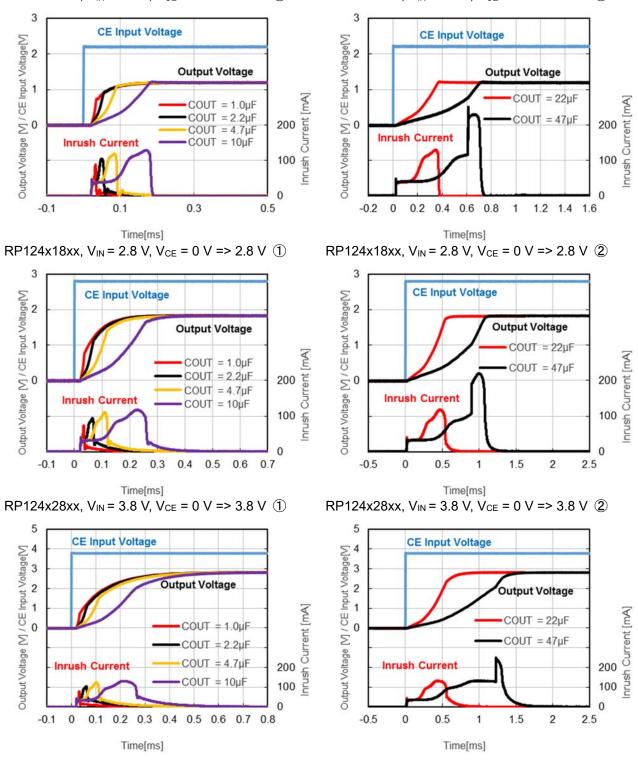
3

CE Input Voltage[V]



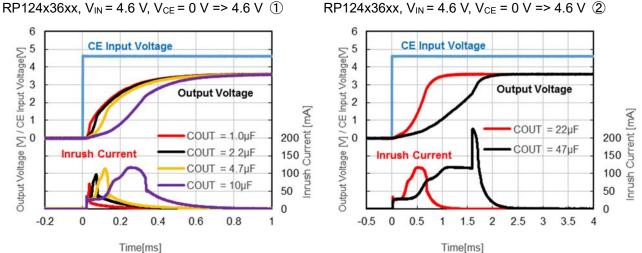
RICOH

No. EA-503-191025

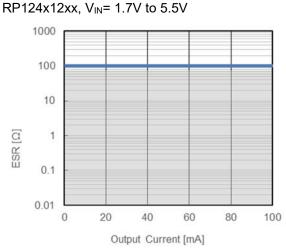


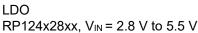
21) Inrush Current at CE Pin's Activation (C_{IN} = Ceramic 0.1 μ F, Ta = 25°C) RP124x12xx, V_{IN} = 2.2 V, V_{CE} = 0 V => 2.2 V ① RP124x12xx, V_{IN} = 2.2 V, V_{CE} = 0 V => 2.2 V ②

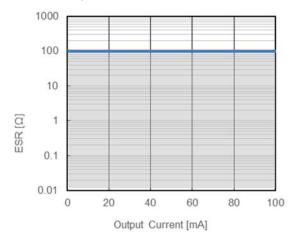
No. EA-503-191025



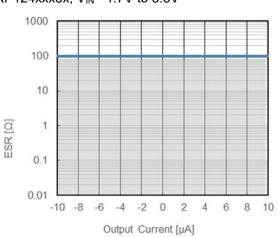
22) ESR vs. Output Current (C_{IN} = Ceramic 1.0 μ F, C_{OUT} = Ceramic 1.0 μ F, C_{BM} = Ceramic 0.1 μ F) Measuring Frequency : 10 Hz to 2 MHz, Ambient Temperature : -40°C to 5°C LDO BM



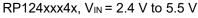


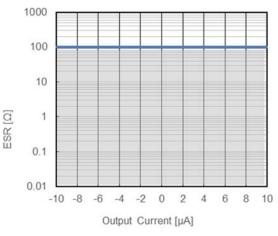


RP124xxx3x, V_{IN} = 1.7V to 5.5V



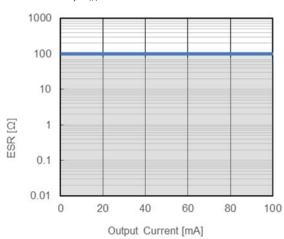






RICOH

No. EA-503-191025



LDO RP124x36xx, V_{IN} = 3.6 V to 5.5 V

RICOH

POWER DISSIPATION

DFN1212-6

Ver. A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Measurement Conditions

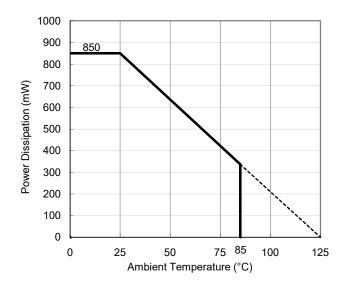
ltem	Measurement Conditions		
Environment	Mounting on Board (Wind Velocity = 0 m/s)		
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)		
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm		
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square		
Through-holes	φ 0.2 mm × 14 pcs		

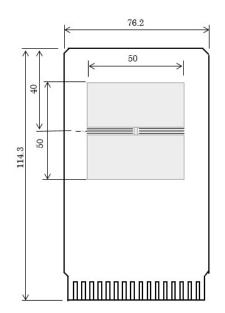
Measurement Result

(Ta = 25°C, Tjmax = 125°C) Item **Measurement Result Power Dissipation** 850 mW Thermal Resistance (0ja) θja = 117°C/W Thermal Characterization Parameter (ψjt) ψ jt = 50°C/W

θja: Junction-to-Ambient Thermal Resistance

wit: Junction-to-Top Thermal Characterization Parameter



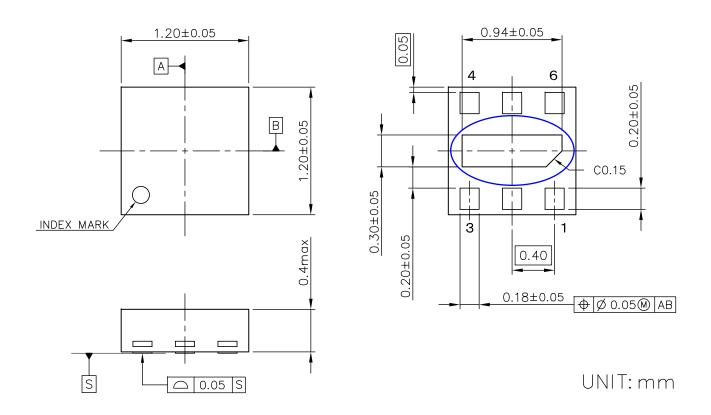


Power Dissipation vs. Ambient Temperature

Measurement Board Pattern

DFN1212-6

Ver. B



DFN1212-6 Package Dimensions

^{*} The tab on the bottom of the package is substrate level (GND). It is recommended that the tab be connected to the ground plane on the board, or otherwise be left floating.



POWER DISSIPATION

SOT-23-5

Ver. A

The power dissipation of the package is dependent on PCB material, layout, and environmental conditions. The following measurement conditions are based on JEDEC STD. 51-7.

Measurement Conditions

ltem	Measurement Conditions		
Environment	Mounting on Board (Wind Velocity = 0 m/s)		
Board Material	Glass Cloth Epoxy Plastic (Four-Layer Board)		
Board Dimensions	76.2 mm × 114.3 mm × 0.8 mm		
Copper Ratio	Outer Layer (First Layer): Less than 95% of 50 mm Square Inner Layers (Second and Third Layers): Approx. 100% of 50 mm Square Outer Layer (Fourth Layer): Approx. 100% of 50 mm Square		
Through-holes	φ 0.3 mm × 7 pcs		

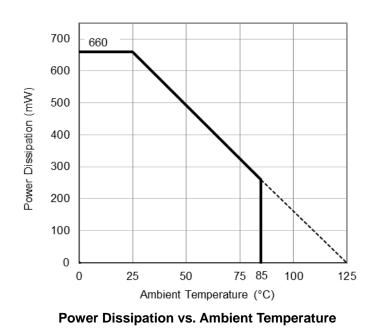
Measurement Result

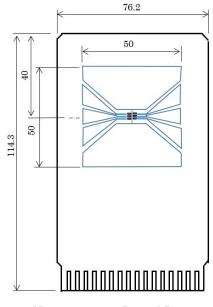
(Ta = 25°C, Tjmax = 125°C)

Item	Measurement Result
Power Dissipation	660 mW
Thermal Resistance (θja)	θja = 150°C/W
Thermal Characterization Parameter (ψjt)	ψjt = 51°C/W

θja: Junction-to-Ambient Thermal Resistance

wjt: Junction-to-Top Thermal Characterization Parameter

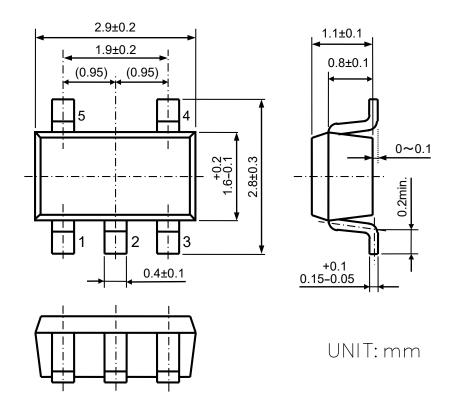




Measurement Board Pattern

SOT-23-5

Ver. A





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